# OSRAM SPL DP91B\_3 **Datasheet**

Preliminary datasheet version





# minary datasheet version

# IR LASER Diode

# SPL DP91B\_3

Nanostack Pulsed Laser Diode









# **Applications**

- 3D Sensing
- Exterior sensing for ADAS

- Robotics

#### **Features**

- Qualifications: The product qualification test plan is based on the guidelines of AEC-Q102, failure mechanism based Stress Test Qualification for Discrete Optoelectronic Semiconductors in Automotive applications.
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- High efficiency
- Narrow emission width and chip size
- 3 vertically nanostacked emitters
- Wavelength stabilisation over temperature

# Ordering Information

Type Peak output power 1) Ordering Code typ.

P<sub>opt</sub>

SPL DP91B\_3 65 W Q65113A4498

# Maximum Ratings

T<sub>A</sub> = 25 °C

Parameter	Symbol		Values
Operating temperature	T <sub>op</sub>	min.	-40 °C
	ор	max.	105 °C
Storage temperature	T <sub>stg</sub>	min.	-40 °C
	Sig	max.	105 °C
Junction temperature	T <sub>j</sub>	max.	125 °C
Forward current	I <sub>F</sub>	max.	20 A
Pulse width (FWHM)	t <sub>P</sub>	max.	50 ns
Duty cycle	D	max.	0.1 %
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	$V_{ESD}$	max.	2 kV

The duty cycle must never exceed 0.1%. This also applies within burst modes. P-Side up die glueing is recommended.

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# **Characteristics**

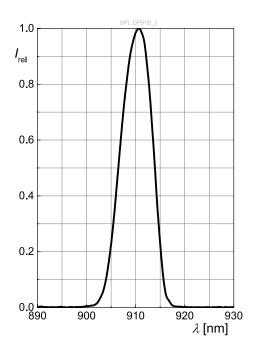
 $t_p$  = 50 ns; D = 0.1 %;  $T_A$  = 25 °C

Parameter	Symbol		Values
Number of emitters	n		3
Spectral bandwidth (FWHM)	Δλ	typ.	7.5 nm
Standard pulse center wavelength $^{2)}$ I <sub>F</sub> = 5.2 A; t <sub>p</sub> = 1 $\mu$ s; D = 0.1 %; T <sub>A</sub> = 25 °C	$oldsymbol{\lambda}_{pulse}$	min. typ. max.	908 nm 912 nm 916 nm
Peak output power 1)	$P_{opt}$	typ.	65 W
Beam divergence (FWHM) parallel to pn-junction	$\Theta_{\parallel}$	typ.	10 °
Beam divergence (FWHM) perpendicular to pn-junction	Θ_	typ.	25 °
Differential efficiency 1)	η	typ.	3.5 W / A
Threshold current	I <sub>th</sub>	typ.	0.5 A
Aperture size (FWHM)	wxh	typ.	110 X 10 μm²
TE polarization TE/(TE+TM), (depends strongly on chip mounting quality)	$P_{TE}$	typ.	98 %

For safety-related applications, 100% final testing needed after assembly at operation conditions.

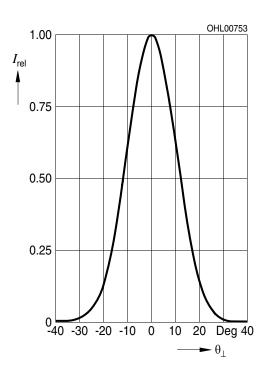
# Relative Spectral Emission 3), 4)

$$I_{e,rel} = f(\lambda); P_{opt} = 65 \text{ W}$$



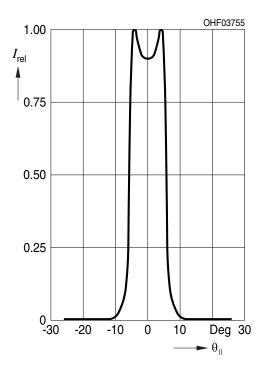
# Far-Field Distribution Perpendicular to pn-Junction 3), 4)

 $I_{e,rel} = f(\Theta_{\perp}); P_{opt} = 65 \text{ W}$ 



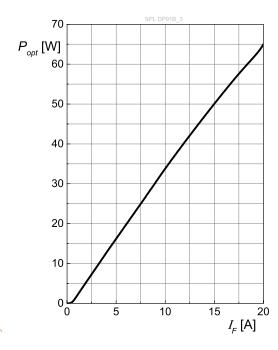
# Far-Field Distribution Parallel to pn-Junction 3), 4)

$$I_{e,rel} = f(\Theta_{II}); P_{opt} = 65 W$$



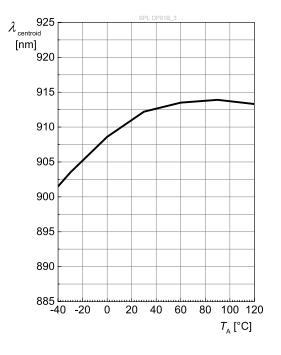
# Optical Output Power 3), 4)

$$P_{opt} = f(I_F)$$



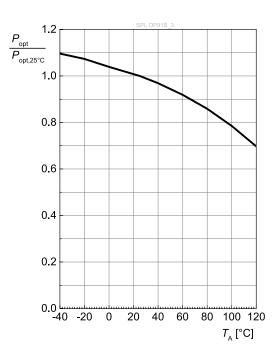
# Centroid Wavelength 3)

$$\lambda_{centroid} = f(T_A); I_F = 20A$$

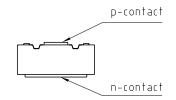


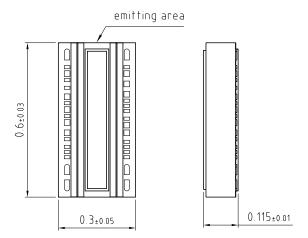
# Peak Output Power 3)

$$P_{opt} = f(T_A); I_F = 20A$$



# **Dimensional Drawing** 5)





#### **Further Information:**

**Approximate Weight:** 0.1 mg

**Notes:** Chip thickness will be safeguarded via statistical process control.

The passive Chip ID structure beside the emitter is intended for chip identifi-

cation only.

#### **Notes**

Depending on the mode of operation, these devices emit highly concentrated visible and non visible light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use.

#### Inked dies

The carrier frame can contain a small amount of defective parts, marked by an ink dot in the center of the defective unit.

The defective parts in each ring are not counted for total delivery quantity and shall not be used by the customer.

For further application related information please visit https://ams-osram.com/support/application-notes



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# Glossary

- 1) Optical power: Optical power measurements refer to an integrating sphere.
- 2) **Wavelength:** The wavelengths are measured with a tolerance of ±1 nm.
- 3) Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 4) **Testing temperature:** TA = 25°C (unless otherwise specified)
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.

# **Revision History**

Version	Date	Change
0.0	2022-12-20	Initial Version
0.1	2024-12-20	Type Designation System

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